

Method for picking up semiconductor chips from a wafer table and method for mounting semiconductor chips on a substrate

FIELD OF THE INVENTION

[0001] The invention relates to a method of the kind mentioned in the preamble of claim 1 for picking up semiconductor chips provided on a wafer table. The invention further relates to a method for mounting the removed semiconductor chips on a substrate.

BACKGROUND OF THE INVENTION

[0002] Mounting machines for the mounting of semiconductor chips are known in the field as die bonders. The mounting machine is used to mount the numerous uniform chips of a wafer which are situated adjacent to one another on a chip carrier one after the other on a substrate, e.g. a metallic lead frame. The die bonder comprises a wafer table on which the chip carrier is situated, a transport system for supplying the substrate and a pick-and-place system in order to remove the semiconductor chips from the chip carrier and place them on the substrate. The pick-and-place system comprises a bonding head with a chip gripper which is moved back and forth by a drive system. The chip gripper is rotatable about a vertical axis, so that the rotational position of the semiconductor chips can be changed if necessary. The chip gripper comprises an exchangeable gripping member, which is a suction member to which vacuum may be applied, which is known in the field as a "pick-up tool" or "die collet".

[0003] Extremely high demands are placed on mounting machines of this kind. They need to be placed in a precise position on the substrate for further processing of the mounted chips. Two cameras are provided on the die bonder to ensure that the semiconductor chips can be placed on the substrate with a precision that lies in the micrometer range. The first camera measures the position of the semiconductor chip to be picked up by the chip gripper and supplies the positional data which relate to a first system of coordinates. The second camera measures the position of the substrate place on which the semiconductor chip needs to be placed and supplies positional data that relate to a second system of coordinates. The pick-and-place system controls the bonding head on the basis of the information supplied by the cameras in such a way that the chip gripper can remove the semiconductor chip from the wafer table and can place the same in a precise positional way at the correct location on the substrate place. The position of the pick-and-place system relates to a third system of coordinates which is independent of the system of coordinates of the camera.

[0004] During operation of the die bonder, the problem arises that the relative position of the three systems of coordinates may change due to different conditions. The temperature at different locations of the die bonder often changes, intentionally or unintentionally. This mostly leads to the consequence that the conversion of target coordinates which were determined in the system of coordinates of the first camera or in the system of coordinates of the second camera into motional coordinates for the pick-and-

place system is no longer as exact as required.

SUMMARY OF THE INVENTION

[0005] The invention is based on the object of providing a method for picking up and mounting semiconductor chips which ensures high precision in placement, irrespective of external circumstances and changes. This object is achieved in accordance with the invention by the features of claim 1.

[0006] The invention relates to a method for picking up and, optionally, mounting semiconductor chips on a substrate, in which

- the semiconductor chips are provided on a wafer table;
- one substrate after the other is provided on a substrate table;
- a first camera detects the position and orientation of the semiconductor chip which is provided on the wafer table and is to be mounted as the next one;
- a second camera detects the position and orientation of the substrate place on which the semiconductor chip will be mounted, and
- a chip gripper picks up the semiconductor chip provided on the wafer table and mounts the same on the substrate, with the chip gripper being held on a bonding head and a pick-and-place system with preferably two linear drives conveys the bonding head with the chip gripper back and forth between the wafer table and the substrate.

[0007] In accordance with the invention, the position of the semiconductor chip to be mounted next as detected by the first camera is provided in the form of positional data relating to a first system of coordinates KS_1 , the position of the substrate place on which the semiconductor chip is to be mounted is provided in the form of positional data relating to a second system of coordinates KS_2 , and the position of the bonding head is related to a third system of coordinates KS_3 .

[0008] The invention proposes providing a marking on the bonding head whose position can be measured by the cameras. Since the marking cannot be arranged in the focal plane of the cameras for constructional reasons, the invention further proposes in a preferred embodiment to attach a lens above the marking, which lens ensures that the marking is also imaged in a sharply defined manner.

[0009] The invention further proposes to use a first fixed mapping function F and a first changeable correction vector K_1 for converting coordinates of the first system of coordinates KS_1 to the third system of coordinates KS_3 of the pick-and-place system, and a second fixed mapping function G and a second changeable correction vector K_2 for the conversion of coordinates of the second system of coordinates KS_2 to the third system of coordinates KS_3 of the pick-and-place system. When the die bonder is set up for the first time or also in the case of a general new setting of the die bonder, the mapping functions F and G and their inverse functions are determined on the one hand and the two correction vectors K_1 and K_2 are set to zero. Whereas the mapping functions F and G are not changed until the next general new

setting of the die bonder, the correction vectors K_1 and K_2 are readjusted upon the occurrence of a predetermined event. A predetermined event shall be understood as being an event in which it can be expected with a high amount of probability that the relative position of the three systems of coordinates KS_1 , KS_2 and KS_3 is changed with respect to each other to an extent that reduces placement precision.

BRIEF DESCRIPTION OF THE DRAWING FIGURES

[0010] The accompanying drawings, which are incorporated into and constitute a part of this specification, illustrate one or more embodiments of the present invention and, together with the detailed description, serve to explain the principles and implementations of the invention. The figures are not shown true to scale.

- Fig. 1 shows a top view of a mounting machine for the mounting of semiconductor chips;
- Fig. 2 shows a side view of a camera, a bonding head and a wafer table, and
- Fig. 3 shows a top view of the bonding head and three different systems of coordinates.

DETAILED DESCRIPTION OF THE INVENTION

[0011] Fig. 1 schematically shows a top view of a mounting machine for mounting semiconductor chips, which is a so-called die bonder, insofar as necessary for the understanding of the invention. Fig. 2 shows parts of the mounting machine in a lateral view. The die bonder comprises a wafer table 1 on which the semiconductor chips 2 to be mounted are provided, a substrate table 3 on which the substrate 4 to be mounted is provided by a transport apparatus (not shown), and a pick-and-place system 5 which picks up the semiconductor chips 2 from the wafer table 1 and places the same on the substrate 4, and two cameras 6 and 7. The pick-and-place system 5 comprises a bonding head 8 with an exchangeable chip gripper 9 (Fig. 2) and two linear, position-controlled drives for moving the bonding head 8 in two orthogonal directions which are designated as the x-direction and y-direction. A third drive (not shown) is used for lifting and lowering the bonding head 8 or the chip gripper 9 in the z-direction which extends perpendicular to the drawing plane. The first camera 6 is used for determining the position of the next semiconductor chip 2 to be removed. The second camera 7 is used to determine the position of the substrate place on the substrate 4 on which the semiconductor chip 2 will be placed. The first camera 6 is usually arranged in a stationary manner. The second camera 7 is also arranged in a stationary manner or can be moved with separate drives in at least one or in two directions extending parallel to the surface of substrate 4. Such pick-and-place systems 5 are known for example from EP 923111, EP 1480507, DE 102004026534 and EP 1612843.

[0012] A marking 10 (Fig. 2) is attached laterally to the bonding head 8 in such a way that it is visible in the image supplied by the first camera 6 when the bonding head 8 is situated in the visual field of the first camera 6, and is visible in the image supplied by the second camera 7 when the bonding head 8 is

situated in the visual field of the second camera 7.

[0013] Fig. 2 shows a side view of the first camera 6, the bonding head 8 and the wafer table 1. Its visual field which is delimited in the drawing by lines 6a faces the wafer table 1, so that in the image as supplied by the same the next semiconductor chip 2 to be removed is imaged in a sharply defined manner. The focal plane of the first camera 6 lies in the plane defined by the semiconductor chip 2 to be removed. The focal plane of the second camera 7 (Fig. 1) lies in the plane defined by the surface of the substrate 4 to be mounted. It is not possible to attach the marking 10 on the bonding head 8 in such a way that it is imaged in a sharply defined manner by both cameras 6 and 7 without adjusting the focal plane. In order to still ensure that the marking 10 is imaged in a sharply defined manner, a lens 10 is advantageously attached to the bonding head 8 above the marking 10. The lens 11 is located between the marking 10 and the respective camera 6 and 7 and ensures that the marking 10 is imaged in sufficiently sharply defined manner in the image of the respective camera 6 and 7. In order to ensure that the marking 10 is imaged in a sharply defined manner, it could also be foreseen to adjust the focal planes of the cameras instead of providing the lens 11. The solution with the lens 11 is simpler, faster and more cost-effective, because as a result of the lens 11 a smaller adjustment range of the lens system of the cameras 6 and 7 is required.

[0014] The first camera 6 supplies its image data to a first image processing unit which determines the position and orientation of the semiconductor chip 2 to be mounted next from the image data and provides them in the form of positional data relating to a first system of coordinates KS_1 . These positional data consist of three numbers (p, q, φ) , with the two numbers p and q designating the position of a reference point of the semiconductor chip 2 and the number φ determining the angle about which the semiconductor chip 2 is rotated against its setpoint position.

[0015] The second camera 7 supplies its image data to a second image processing unit which determines the position and orientation of the substrate place from the image data on which the semiconductor chip 2 will be mounted, and provides them in the form of positional data relating to a second system of coordinates KS_2 . These positional data consist of three numbers (u, v, ψ) , with the numbers u and v designating the position of a reference point of the substrate place and the number ψ the angle about which the substrate place is rotated against its setpoint position.

[0016] The first linear drive of the pick-and-place systems supplies a number x_M and the second linear drive of the pick-and-place systems supplies a number y_M , which together form the positional data which represent the position (x_M, y_M) of the marking 10 with respect to the third system of coordinates KS_3 .

[0017] The chip gripper 9 is rotatable about a rotational axis 12 (Fig. 2). The suction opening of chip

gripper 9 defines the position of the gripper axis 13 (Fig. 2) of chip gripper 9. The position (x_G, y_G) of the gripper axis 13 in the third system of coordinates KS_3 is given by

$$(x_G, y_G) = (x_M, y_M) + D + E$$

with vector D describing the position of rotational axis 12 relative to the position (x_M, y_M) of the marking 10 and vector E the position of the gripper axis 13 relative to the position of the rotational axis 12. Vector D is a fixed vector which is to be determined once. Vector E is a vector which co-rotates with the chip gripper 9: Its length has a fixed amount, but its direction changes when the chip gripper 9 is rotated about the rotational axis 12. In the ideal case, the rotational axis 12 and the gripper axis 13 always coincide, i.e. $E = 0$, irrespective of the rotational position of the chip gripper 9.

[0018] Fig. 3 illustrates the correlation between the three system of coordinates KS_1 , KS_2 and KS_3 . In order to ensure that the semiconductor chips 2 can be placed on the substrate 4 in a correctly positioned manner, it must be possible to calculate the current position of the gripper axis 13 of the chip gripper 9 both in the first system of coordinates KS_1 and in the second system of coordinates KS_2 . A first mapping function F is therefore determined in the first-time setup or general new setting of the mounting machine, which function F maps the first system of coordinates KS_1 to the third system of coordinates KS_3 . This occurs with the help of the marking 10: The two linear drives of the pick-and-place systems 5 move the bonding head 8 with the marking 10 to a number k of different positions (x_n, y_n) with $n = 1$ to k within the visual field of the first camera 6, and the first image processing unit determines from the image supplied by the first camera 6 the pertinent position (p_n, q_n) of marking 10. The first mapping function F is calculated from the obtained data records. The following then applies:

$$(x, y) = F(p, q)$$

The inverse function F^{-1} of the mapping function F is then calculated, so that

$$(p, q) = F^{-1}(x, y)$$

Furthermore, a first correction vector K_1 is set to the value $K_1 = 0$.

[0019] In analogy to this, a second mapping function G that maps the second system of coordinates KS_2 to the third system of coordinates KS_3 and its inverse function G^{-1} are determined. The following then applies:

$$(x, y) = G(u, v)$$

and vice-versa

$$(u, v) = G^{-1}(x, y)$$

Furthermore, a second correction vector K_2 is set to the value $K_2 = 0$.

[0020] The first camera 6 and the first system of coordinates KS_1 are used in order to determine the target coordinates relating to the first system of coordinates KS_1 to which the pick-and-place system 5 must move the bonding head 8 so that the chip gripper 9 can take up the semiconductor chip 2 provided on the wafer table 1. The second camera 7 and the second system of coordinates KS_2 are used in order to

determine the target coordinates relating to the second system of coordinates KS_2 to which the pick-and-place system 5 must move the bonding head 8 so that the chip gripper 9 can place the semiconductor chip 2 in a correctly positioned manner. All calculations are performed in these two systems of coordinates KS_1 and KS_2 . Only after the completion of all calculations will the determined target coordinates be converted into the coordinates of motion of the third system of coordinates KS_3 by means of the respective mapping function F and G . Vectors D and E are therefore determined both as vectors D_1 and E_1 relating to the first system of coordinates KS_1 and as vectors D_2 and E_2 relating to the second system of coordinates KS_2 . The third system of coordinates KS_3 is therefore only used to move the bonding head 8 without making any calculations in this system of coordinates KS_3 . The third system of coordinates KS_3 is given by the mechanics of the pick-and-place system 5, i.e. the coordinates x and y are the positional values supplied by the encoders of the two linear drives and is therefore not an exact orthogonal system of coordinates.

[0021] Once the mapping functions F and G , their inverse functions F^{-1} and G^{-1} and the vectors D_1 , E_1 , D_2 and E_2 have been determined, one semiconductor chip 2 after the other can be mounted in the production phase in that

- an image is taken of the next semiconductor chip 2 by first camera 6 and the positional data (p_w, q_w, φ_w) relating to first system of coordinates KS_1 of the semiconductor chip 2 are calculated from the image, whereby $\varphi_w = 0$ when the semiconductor chip 2 is not rotated against its setpoint position;
- the position (x_w, y_w) relating to the third system of coordinates KS_3 which needs to be taken by the marking 10 so that the gripper axis 13 of the chip gripper 9 passes through the reference point of the semiconductor chip 2 is calculated as

$$(x_w, y_w) = F [(p_w, q_w) - D_1 - E_1 + K_1]$$

- the calculated position (x_w, y_w) is approached and the semiconductor chip 2 is taken up by the chip gripper 9;
- an image of the substrate place is taken by the second camera 7 on which the semiconductor chip 2 will be mounted, and the positional data (u_s, v_s, ψ_s) of the substrate place relating to the second system of coordinates KS_2 are calculated from the image, whereby $\psi_s = 0$ when the substrate place is not rotated against its setpoint position;
- the position (x_s, y_s) relating to the third system of coordinates KS_3 which needs to be taken by the marking 10 so that the gripping axis 13 of the chip gripper 9 passes through the reference point of the substrate place is calculated as

$$(x_s, y_s) = G [(u_s, v_s) - D_2 - E_2 + K_2]$$

- the calculated position (x_s, y_s) is approached, the chip gripper 9 is optionally rotated about the angle $\psi_s - \varphi_s$, and the semiconductor chip 2 is placed on the substrate place.

[0022] In order to keep the placement precision of the die bonder at the same high level during the

entire production, a readjustment of the first correction vector K_1 and the second correction vector K_2 is performed during the occurrence of a predetermined event. The marking 10 provided on the bonding head 8 is used, which marking is brought into the visual field of the first camera 6 for readjusting the first correction vector K_1 and into the visual field of the second camera 7 for readjusting the second correction vector K_2 . The readjustment of the first correction vector K_1 occurs by:

- Moving the bonding head 8 to a setpoint position $R = (x_R, y_R)$ in which the marking 10 is located in the visual field of the first camera 6, with the coordinates (x_R, y_R) relating to the third system of coordinates KS_3 ;
- calculating the setpoint position (p_R, q_R) of the marking 10 with respect to the first system of coordinates KS_1 as $(p_R, q_R) = F^{-1}(x_R, y_R)$;
- taking an image of the marking 10 with the first camera 6, using the image of the first camera 6 for determining the actual position (p_M, q_M) of the marking 10 with respect to the first system of coordinates KS_1 , and
- calculating the first correction vector K_1 as difference between the approached setpoint position and the measured actual position:

$$K_1 = (p_R, q_R) - (p_M, q_M).$$

It is clear that the first correction vector K_1 relates to the first system of coordinates KS_1 .

[0023] The readjustment of the second correction vector K_2 occurs analogously by

- moving the bonding head 8 to a setpoint position $T = (x_T, y_T)$ in which the marking 10 is located in the visual field of the second camera 7, with the coordinates (x_T, y_T) relating to the third system of coordinates KS_3 ;
- calculating the setpoint position (u_T, v_T) of the marking 10 with respect to the second system of coordinates KS_2 into $(u_T, v_T) = G^{-1}(x_T, y_T)$;
- taking an image of the marking 10 with the second camera 7, using the image of the camera 7 for determining the actual position (u_M, v_M) of the marking 10 with respect to the second system of coordinates KS_2 , and
- calculating the second correction vector K_2 as difference between the approached setpoint position and the measured actual position:

$$K_2 = (u_T, v_T) - (u_M, v_M),$$

It is clear that the second correction vector K_2 relates to the second system of coordinates KS_2 .

[0024] There are different events that can trigger a readjustment of the correction vectors K_1 and K_2 , especially the following four events:

- since the last calibration a predetermined number of semiconductor chips 2 have been mounted;
- since the last calibration a temperature measured at a predetermined location of the pick-and-place systems 5 has changed by more than a predetermined value;

- production was stopped;
- the actual position of the mounted semiconductor chip which was detected and calculated by the second camera 7 after mounting deviates from the setpoint position by more than a predetermined amount.

[0025] After the completion of the readjustment of the correction vectors K_1 and K_2 , the mounting of the semiconductor chips 2 can be continued according to the steps as described above, but the updated correction vectors K_1 and K_2 can now differ from zero.

[0026] The invention can be applied in the known pick-and-place systems in which the wafer table 1 and the platform 3 for the substrates 4 are arranged in parallel planes, as well as in the pick-and-place system as described in EP 1480507 in which the wafer table 1 and the platform 3 for the substrates are arranged in an oblique manner relative to each other and in which the bonding head 8 performs a pivoting movement about a horizontal axis in addition to the movement in the x-direction and y-direction.

[0027] The embodiment as described above is a preferred embodiment, in which the bonding head is moved for adjustment and readjustment to the first setpoint position R and to the second setpoint position T, respectively, and the coordinates of the first setpoint position R and the second setpoint position T relating to the third system of coordinates KS_3 are stored and are used for readjusting the two correction vectors K_1 and K_2 . In this example, the respective setpoint position of the marking 10 is calculated by means of the inverse function F^{-1} and G^{-1} , respectively. A further embodiment is explained below in which the coordinates of the marking 10 (or any other random reference point on the bonding head 8) relating to the first system of coordinates KS_1 or the coordinates of the marking 10 (or any other random reference point on the bonding head 8) relating to the second system of coordinates KS_2 are stored additionally when the bonding head 8 is located in the first or second setpoint position, and are then used for readjustment of the two corrections vectors K_1 and K_2 .

[0028] The pick-and-place system comprises as a part the pick system for picking up the semiconductor chips from the wafer table. The third system of coordinates KS_3 is a coordinate system immanent to the pick system or the pick-and-place system and will therefore be referred to below as system of coordinates KS. To ensure that the readjustment can be performed, an adjustment is performed at first in a setup phase in which the bonding head 8 is moved to a first setpoint position which is located in the visual field of first camera 6 and the coordinates (x_{SP1}, y_{SP1}) of the first setpoint position relating to the system of coordinates KS and the coordinates (p_{SP1}, q_{SP1}) of the first setpoint position relating to the system of coordinates KS_1 of the first camera 6 are determined and stored. The readjustment occurs in the production phase in such a way that the bonding head 8 is moved to the coordinates (x_{SP1}, y_{SP1}) of the first setpoint position and the coordinates (p_{SP1}', q_{SP1}') of the setpoint position relating to the system of

coordinates KS_1 of the first camera 6 are determined again. The difference vector $(p_{SP1}', q_{SP1}') - (p_{SP1}, q_{SP1})$ contains the information about the displacement of the first system of coordinates KS_1 with respect to the system of coordinates KS which has occurred since the setup in the setup phase. Any random reference point on the bonding head 8 can be used for defining the first setpoint position of the bonding head 8 with respect to the first system of coordinates KS_1 . The above mentioned marking 10 is preferably used for the definition of the reference point.

[0029] In an analogous manner, displacements of the second system of coordinates KS_2 of the second camera 7 are detected and corrected with respect to the system of coordinates KS of the bonding head 8, such that in the setup phase a further adjustment is performed in which the bonding head 8 is moved to a second setpoint position which is located in the visual field of the second camera 7 and the coordinates (x_{SP2}, y_{SP2}) of the second setpoint position relating to the system of coordinates KS and the coordinates (u_{SP2}, v_{SP2}) of the second setpoint position relating to the system of coordinates KS_2 of the second camera 7 are determined and stored. The readjustment in the production phase occurs in such a way that the bonding head 8 is moved to the coordinates (x_{SP2}, y_{SP2}) of the second setpoint position and the coordinates (u_{SP2}', v_{SP2}') of the second setpoint position which relate to the system of coordinates KS_2 of the second camera 7 are determined again. The difference vector $(u_{SP2}', v_{SP2}') - (u_{SP2}, v_{SP2})$ contains the information about the displacement of the second system of coordinates KS_2 with respect to the system of coordinates KS which has occurred since the setup in the setup phase. In this case too, any random reference point on the bonding head 8 can be used for the definition of the second setpoint position of the bonding head 8 with respect to the second system of coordinates KS_2 . The marking 10 as mentioned above is preferably used for the definition of the reference point.

[0030] The determination of the coordinates of the reference points relating to the first system of coordinates KS_1 and the second system of coordinates KS_2 comprises the taking of an image with the respective camera 6 and 7 and the determination of the coordinates of the reference point by means of conventional image evaluation.

[0031] The mounting of the semiconductor chips then preferably occurs in such a way that

- the position of the semiconductor chip 2 to be mounted next, as detected by the first camera 6, is provided in the form of positional data relating to the first system of coordinates KS_1 ;
- the position of the substrate place on which semiconductor chip 2 is to be mounted, as detected by the second camera 7, is provided in the form of positional data relating to the second system of coordinates KS_2 ;
- in the setup phase, a first mapping function which maps the first system of coordinates KS_1 to the system of coordinates KS and its inverse function are determined, a first correction vector is set to the value zero, a second mapping function which maps the second system of coordinates KS_2 to the coordinate system KS and its inverse function are determined, and a second correction vector is set to

the value zero;

- one semiconductor chip 2 after another is mounted in the production phase, such that
 - an image of the semiconductor chip 2 that will be mounted next is taken with the camera 6 and the position of the semiconductor chip 2 with respect to the first system of coordinates KS_1 is determined, and the position, to which the pick-and-place system 5 needs to move the bonding head 8 in order to pick up the semiconductor chip 2, in relation to the system of coordinates KS is calculated therefrom by means of the first mapping function and by taking into account the first correction vector;
 - an image of the substrate place on which the semiconductor chip 2 will be mounted is taken with the second camera 7, and the position of the substrate place with respect to the second system of coordinates KS_2 is determined, and the position, to which position the pick-and-place system 5 needs to move the bonding head 8 in order to mount the semiconductor chip 2 on the substrate place, in relation to the system of coordinates KS is calculated therefrom by means of the second mapping function and by taking into account the second correction vector;
- and that the readjustment in the production phase comprises a readjustment of the first correction vector and the second correction vector with the following steps:
- moving the bonding head 8 to the first setpoint position;
 - taking an image of the marking 10 with the first camera 6, and determining the actual position of the marking 10 with respect to the first system of coordinates KS_1 from the image of the first camera 6, and
 - calculating the first correction vector K_1 as difference between the stored setpoint position and the determined actual position;
 - moving the bonding head 8 to the second setpoint position;
 - taking the image of the marking 10 with the second camera 7, and determining the actual position of the marking 10 with respect to the second system of coordinates KS_2 from the image of the second camera 7, and
 - calculating the second correction vector K_2 as difference between the stored setpoint position and the determined actual position.

[0032] While embodiments and applications of this invention have been shown and described, it would be apparent to those skilled in the art having the benefit of this disclosure that many more modifications than mentioned above are possible without departing from the inventive concepts herein. The invention, therefore, is not to be restricted except by the appended claims and their equivalents.

CLAIMS:

1. Method for picking up semiconductor chips (2) provided on a wafer table (1), in which a first camera (6) detects the position of a provided semiconductor chip and a chip gripper (9) held on a bonding head (8) picks up the semiconductor chip (2), with the bonding head (8) with the chip gripper (9) being movable by means of a pick system according to a system of coordinates KS immanent to the pick system, **characterized in that** in a setup phase an adjustment of a first setpoint position of the bonding head (8) is performed which first setpoint position is located in the visual field of the first camera (6), with the bonding head (8) being moved to the first setpoint position during the adjustment and the coordinates of the first setpoint position relating to the system of coordinates KS and the coordinates of the first setpoint position relating to a system of coordinates KS_1 of the first camera (6) being determined and stored, and that in a production phase a readjustment of the first setpoint position is performed at the occurrence of a predetermined event.
2. Method according to claim 1, in which a marking (10) is applied to the bonding head (8), **characterized in that** the coordinates of the first setpoint position relating to the system of coordinates KS_1 of the first camera (6) represent the position of the marking.
3. Method for mounting semiconductor chips on a substrate which comprises a method according to claim 1 or 2 and in which a second camera (7) detects the position of a substrate place on which the semiconductor chip (2) picked up by the chip gripper (9) is to be mounted, with the pick system being part of a pick-and-place system which enables picking up the semiconductor chip from the wafer table and mounting the semiconductor chip on the substrate.
4. Method for mounting semiconductor chips according to claim 3, **characterized in that** in the setup phase an adjustment of a second setpoint position of the bonding head (8) is performed, which second setpoint position is located in the visual field of the second camera (7), with the bonding head (8) being moved to the second setpoint position during the adjustment, and the coordinates of the second setpoint position relating to the system of coordinates KS and the coordinates of the second setpoint position relating to the system of coordinates KS_2 of the second camera (7) are determined and stored, and that in the production phase a readjustment of the second setpoint position is performed at the occurrence of a predetermined event.
5. Method according to claim 4, **characterized in that** the coordinates of the second setpoint position relating to the system of coordinates KS_2 of the second camera (7) represent the position of the marking (10).
6. Method according to any of claims 3 to 5, **characterized in that**
 - the position of the semiconductor chip (2) to be mounted next, as detected by the first camera (6), is

provided in the form of positional data relating to the first system of coordinates KS_1 ;

- the position of the substrate place on which the semiconductor chip (2) is to be mounted, as detected by the second camera (7), is provided in the form of positional data relating to the second system of coordinates KS_2 ;
 - in the setup phase, a first mapping function which maps the first system of coordinates KS_1 to the system of coordinates KS and its inverse function are determined, a first correction vector is set to the value zero, a second mapping function which maps the second system of coordinates KS_2 to the coordinate system KS and its inverse function are determined, and a second correction vector is set to the value zero;
 - in the production phase one semiconductor chip (2) after the other is mounted, in that
 - an image of the semiconductor chip (2) that is to be mounted next is taken with the first camera (6) and the position of the semiconductor chip (2) with respect to the first system of coordinates KS_1 is determined, and the position, to which the pick-and-place system (5) needs to move the bonding head (8) in order to pick up the semiconductor chip (2), in relation to the system of coordinates KS is calculated therefrom by means of the first mapping function and by taking into account the first correction vector;
 - an image of the substrate place on which the semiconductor chip (2) is to be mounted is taken with the second camera (7), and the position of the substrate place with respect to the second system of coordinates KS_2 is determined, and the position, to which the pick-and-place system (5) needs to move the bonding head (8) in order to mount the semiconductor chip (2) on the substrate place, in relation to the system of coordinates KS is calculated therefrom by means of the second mapping function and by taking into account the second correction vector;
- and that the readjustment in the production phase comprises a readjustment of the first and second correction vector with the following steps:
- moving the bonding head (8) to the first setpoint position;
 - taking an image of the marking (10) with the first camera (6), and determining the actual position of the marking (10) with respect to the first system of coordinates KS_1 from the image of the first camera (6), and
 - calculating the first correction vector K_1 as difference between the stored or calculated setpoint position and the determined actual position;
 - moving the bonding head (8) to the second setpoint position;
 - taking an image of the marking (10) with the second camera (7), and determining the actual position of the marking (10) with respect to the second system of coordinates KS_2 from the image of the second camera (7), and
 - calculating the second correction vector as difference between the stored or calculated setpoint position and the determined actual position.

7. Method according to any of claims 1 to 6, **characterized in that** the event is at least one of the following events:

- since the last calibration a predetermined number of semiconductor chips (2) have been mounted;
- since the last calibration a temperature measured at a predetermined location of the pick-and-place system (5) has changed by more than a predetermined value;
- production was stopped;
- the actual position of the mounted semiconductor chip which was detected and calculated by the second camera (7) after mounting deviates from the setpoint position by more than a predetermined amount.

8. Method according to any of claims 2 to 7, **characterized in that** the marking (10) applied to the bonding head (8) is imaged with sufficient sharpness onto the respective camera (6 and 7) by means of a lens (11) attached to the bonding head (8).